The New Standard for Performance, Power and Reliability

Micron’s Hybrid Memory Cube (HMC) is a fundamental and revolutionary change in DRAM architecture.

Using advanced 3-D packaging that leverages through-silicon-via (TSV) technology, we have combined advanced logic and DRAM layers into one optimized package. The result is a category of memory unlike anything on the market today.

With performance levels that break through the memory wall, HMC delivers a high-bandwidth, energy-efficient, high-density memory system that will enrich next-generation networking, drive significant reductions in data center power consumption, and enable exascale supercomputing.

Learn More

Ongoing efforts by the Hybrid Memory Cube Consortium (HMCC) have established a solid ecosystem for this exciting technology that continues to expand with a growing number of adopters. The consortium is managed by a team of eight industry leaders, with well over 150 additional organizations pursuing adopter status.

Visit www.hybridmemorycube.org to learn more about the HMCC or to become an HMC Adopter and participate in the early market review and discussion of the HMC specification.

BENEFITS

Increased Bandwidth
15X the bandwidth of a DDR3 module

Power-Efficient
70% less energy usage per bit than existing technologies

Smaller Size
Uses nearly 90% less space than today’s RDIMMs

Scalable
Can be tailored to multiple platforms and applications

Reduced Latency
Massive parallelism enables significantly lower latency